

Title (en)
METHOD FOR MANUFACTURING A CHIP CARD

Title (de)
VERFAHREN ZUM HERSTELLEN EINER CHIPKARTE

Title (fr)
MODE DE FABRICATION D'UNE CARTE A PUCE

Publication
EP 1008103 A1 20000614 (DE)

Application
EP 97952785 A 19971119

Priority
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• EP 9706469 W 19971119

Abstract (en)
[origin: DE19647846C1] In the method, a semiconductor chip module is inserted in a recess (2) in the surface of the card carrier (1), in electrical contact with an inductive signal transmission device provided by an antenna coil (3). The antenna coil, or its end terminations (4) are located within the recess for the semiconductor chip module and wound in a spiral for absorbing the flexure and/or torsion forces in the vicinity of the semiconductor chip module connections.

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See references of WO 9822906A1

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